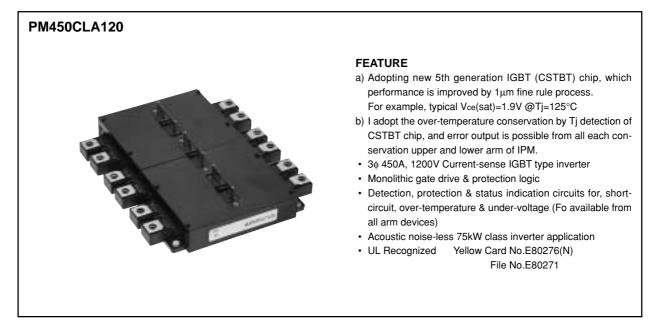
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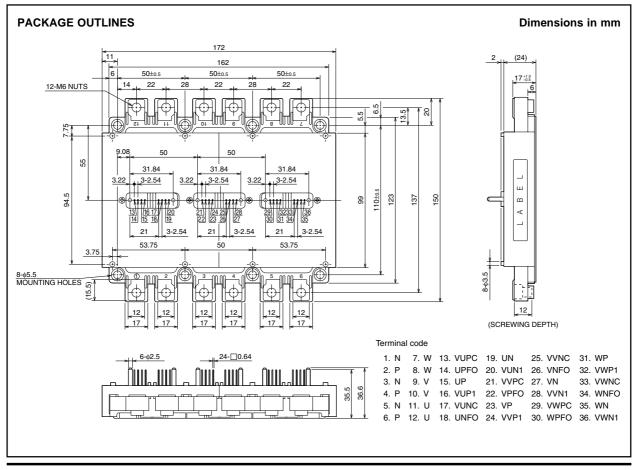
PM450CLA120

FLAT-BASE TYPE INSULATED PACKAGE



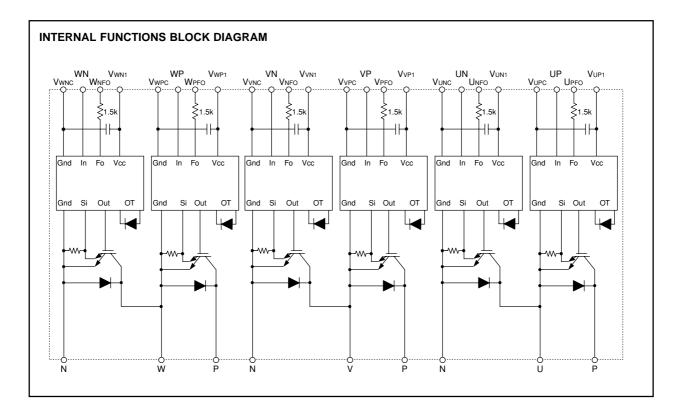
APPLICATION

General purpose inverter, servo drives and other motor controls





FLAT-BASE TYPE INSULATED PACKAGE



MAXIMUM RATINGS (Tj = 25° C, unless otherwise noted) **INVERTER PART**

Symbol	Parameter	Condition	Ratings	Unit
VCES	Collector-Emitter Voltage	VD = 15V, VCIN = 15V	1200	V
±lc	Collector Current	Tc = 25°C	450	Α
±IСР	Collector Current (Peak)	Tc = 25°C	900	Α
Pc	Collector Dissipation	$Tc = 25^{\circ}C$ (Note-1)	2500	W
Tj	Junction Temperature		-20 ~ +150	°C

CONTROL PART

Symbol	Parameter	Condition	Ratings	Unit
VD	Supply Voltage	Applied between : VUP1-VUPC, VVP1-VVPC, VWP1-VWPC	20	v
VD	Supply Voltage	VUN1-VUNC, VVN1-VVNC, VWN1-VWNC	20	v
VCIN Input Voltage		Applied between : UP-VUPC, VP-VVPC, WP-VWPC	20	V
VCIN	Input Voltage	UN-VUNC, VN-VVNC, WN-VWNC	20	v
	Fault Output Supply Voltage	Applied between : UPFO-VUPC, VPFO-VVPC, WPFO-VWPC	00	V
Vfo		UNFO-VUNC, VNFO-VVNC, WNFO-VWNC	20	v
	Fault Output Current	Sink current at UPFO, VPFO, WPFO, UNFO, VNFO, WNFO	00	
IFO		terminals	20	mA



FLAT-BASE TYPE **INSULATED PACKAGE**

TOTAL SYSTEM

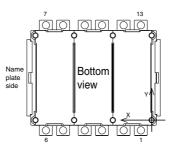
Symbol	Parameter	Condition	Ratings	Unit
VCC(PROT)	Supply Voltage Protected by SC	$VD = 13.5 \sim 16.5V$, Inverter Part, Tj = +125°C Start	800	v
VCC(surge)	Supply Voltage (Surge)	Applied between : P-N, Surge value	1000	V
Tstg	Storage Temperature		-40 ~ +125	°C
Viso	Isolation Voltage	60Hz, Sinusoidal, Charged part to Base, AC 1 min.	2500	Vrms

THERMAL RESISTANCES

Symbol Parameter		Condition		Limits			
				Тур.	Max.	Unit	
Rth(j-c)Q	Junction to case Thermal	Inverter IGBT (per 1 element) (Note-1)	_	_	0.05		
Rth(j-c)F	Resistances	Inverter FWDi (per 1 element) (Note-1)	—	—	0.09	°C/W	
Rth(c-f)	O and a st The survey I De sister as a	Case to fin, (per 1 module)		_	0.014	0/00	
nui(0-1)	Contact Thermal Resistance	Thermal grease applied (Note-1)	-				

(Note-1) Tc measurement point is just under the chip. If you use this value, $Rth(f\mbox{-}a)$ should be measured just under the chips.

Table	Table 1: Tc (under the chip) measurement point is below. (Unit									t : mm)			
	arm	U	Р	V	Р	N	/P	U	N	V	N	W	'N
axis		IGBT	FWDi	IGBT	FWDi	IGBT	FWDi	IGBT	FWDi	IGBT	FWDi	IGBT	FWDi
	Х	30.1	19.2	80.1	69.2	130.1	119.2	19.8	30.7	69.8	80.7	119.8	130.7
	Y	82.7	82.7	82.7	82.7	82.7	82.7	27.2	27.2	27.2	27.2	27.2	27.2



ELECTRICAL CHARACTERISTICS (Tj = 25°C, unless otherwise noted)	
INVERTER PART	

Ourseland	abol Parameter Condition				Limits			
Symbol	Parameter	Condition			Min.	Тур.	Max.	Unit
	Collector-Emitter	VD = 15V, IC = 450A		Tj = 25°C		1.8	2.3	V
VCE(sat)	Saturation Voltage	VCIN = 0V (F	ig. 1)	Tj = 125°C		1.9	2.4	v
VEC	FWDi Forward Voltage	-IC = 450A, VD = 15V, VCIN = 15V	/	(Fig. 2)		2.8	3.9	V
ton					0.5	1.0	2.5	
trr		$VD = 15V, VCIN = 0V \leftrightarrow 15V$			—	0.5	0.8	
tc(on)	Switching Time	VCC = 600V, IC = 450A				0.4	1.0	μs
toff		Tj = 125°C		(5 - 0 - 4)	_	2.3	3.5	
tc(off)		Inductive Load		(Fig. 3, 4)		0.7	1.2	
1050	Collector-Emitter		·	Tj = 25°C	_	_	1	
ICES	Cutoff Current	VCE = VCES, VCIN = 15V (F	(Fig. 5)	Tj = 125°C	_	_	10	mA



FLAT-BASE TYPE INSULATED PACKAGE

CONTROL PART

Symbol Parameter							
		Condition	Condition		Тур.	Max.	Unit
ID	Circuit Current	VD = 15V. VCIN = 15V	V*N1-V*NC		20	27	m (
U		VD = 15V, VCIN = 15V	V*P1-V*PC		20	27	mA
Vth(ON)	Input ON Threshold Voltage	Applied between : UP-VUPC, VP-VVPC,	WP-VWPC	1.2	1.5	1.8	v
Vth(OFF)	Input OFF Threshold Voltage	UN-VUNC, VN-VVNC, V	WN-VWNC	1.7	2.0	2.3	v
SC	Short Circuit Trip Level	$-20 \le T_j \le 125^{\circ}C, V_D = 15V$	(Fig. 3,6)	900	_	_	Α
toff(SC)	Short Circuit Current Delay Time	VD = 15V	(Fig. 3,6)	_	0.2	_	μs
OT	Over Temperature Protection	VD = 15V	Trip level	135	145	_	°C
OTr	Over lemperature Protection	Detect Tj of IGBT chip	Reset level	_	125	_	Ŭ
UV	Supply Circuit Under-Voltage	–20 ≤ Ti ≤ 125°C	Trip level	11.5	12.0	12.5	v
UVr	Protection	-20 ≤ 1] ≤ 125 C	Reset level	_	12.5	_	v
IFO(H)	- Fault Output Current	VD = 15V, VFO = 15V	(Note-2)	-	_	0.01	mA
IFO(L)		VD = 15V, VFO = 15V	(11018-2)	_	10	15	IIIA
tFO	Minimum Fault Output Pulse Width	VD = 15V	(Note-2)	1.0	1.8	_	ms

(Note-2) Fault output is given only when the internal SC, OT & UV protections schemes of either upper or lower arm device operate to protect it.

MECHANICAL RATINGS AND CHARACTERISTICS

	D i Condition				Unit		
Symbol	Parameter	Condition	Min.	Тур.	Max.	Unit	
—	Mounting torque	Main terminal	screw : M6	3.5	4.0	4.5	N۰m
—	Mounting torque	Mounting part	screw : M5	2.5	3.0	3.5	N•m
_	Weight	—			1250	_	g

RECOMMENDED CONDITIONS FOR USE

Symbol	Parameter	Condition	Recommended value	Unit
Vcc	Supply Voltage	Applied across P-N terminals	≤ 800	V
		Applied between : VUP1-VUPC, VVP1-VVPC, VWP1-VWPC		
VD	Control Supply Voltage	VUN1-VUNC, VVN1-VVNC, VWN1-VWNC	15 ± 1.5	V
		(Note-3)		
VCIN(ON)	Input ON Voltage	Applied between : UP-VUPC, VP-VVPC, WP-VWPC	≤ 0.8	v
VCIN(OFF)	Input OFF Voltage	UN-VUNC, VN-VVNC, WN-VWNC	≥ 9.0	7 °
fрwм	PWM Input Frequency	Using Application Circuit of Fig. 8	≤ 20	kHz
tdead	Arm Shoot-through Blocking Time	For IPM's each input signals (Fig. 7)	≥ 3.0	μs

(Note-3) With ripple satisfying the following conditions: dv/dt swing $\leq \pm 5 V/\mu s, \, Variation \leq 2 V$ peak to peak



FLAT-BASE TYPE **INSULATED PACKAGE**

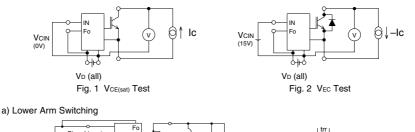
PRECAUTIONS FOR TESTING

1. Before appling any control supply voltage (VD), the input terminals should be pulled up by resistores, etc. to their corresponding supply voltage and each input signal should be kept off state.

After this, the specified ON and OFF level setting for each input signal should be done.

2. When performing "SC" tests, the turn-off surge voltage spike at the corresponding protection operation should not be allowed to rise above VCES rating of the device.

(These test should not be done by using a curve tracer or its equivalent.)



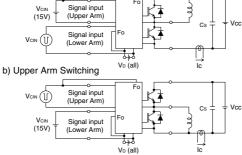


Fig. 3 Switching time and SC test circuit

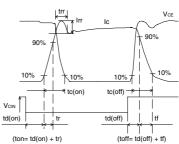
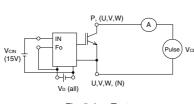
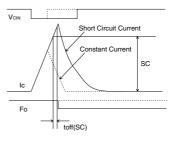


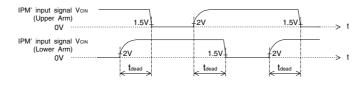
Fig. 4 Switching time test waveform











1.5V: Input on threshold voltage Vth(on) typical value, 2V: Input off threshold voltage Vth(off) typical value





FLAT-BASE TYPE INSULATED PACKAGE

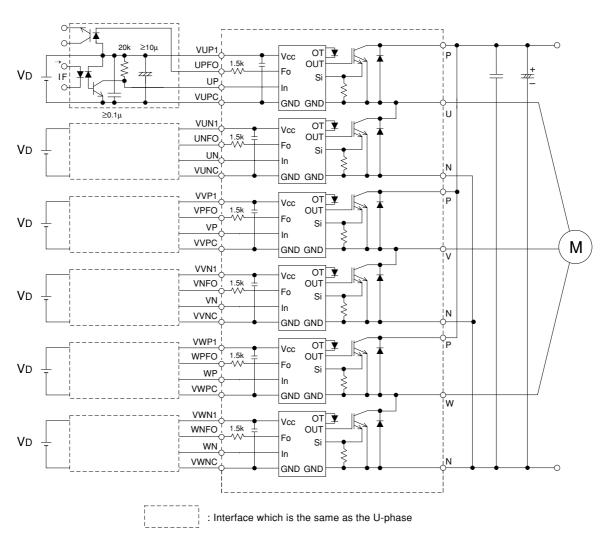


Fig. 8 Application Example Circuit

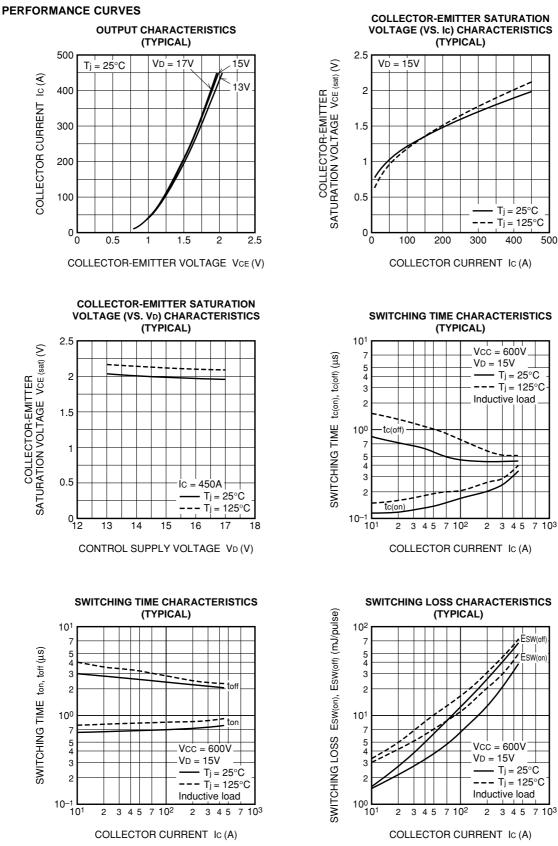
NOTES FOR STABLE AND SAFE OPERATION ;

- Design the PCB pattern to minimize wiring length between opto-coupler and IPM's input terminal, and also to minimize the stray capacity between the input and output wirings of opto-coupler.
- Connect low impedance capacitor between the Vcc and GND terminal of each fast switching opto-coupler.
- Fast switching opto-couplers: tPLH, tPHL ≤ 0.8µs, Use High CMR type.
- Slow switching opto-coupler: CTR > 100%
- Use 6 isolated control power supplies (VD). Also, care should be taken to minimize the instantaneous voltage charge of the power supply.
- Make inductance of DC bus line as small as possible, and minimize surge voltage using snubber capacitor between P and N terminal.
- Use line noise filter capacitor (ex. 4.7nF) between each input AC line and ground to reject common-mode noise from AC line and improve noise immunity of the system.



FLAT-BASE TYPE **INSULATED PACKAGE**

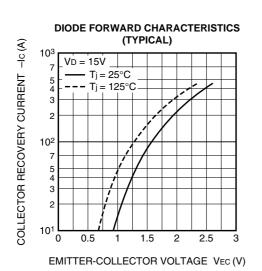
500

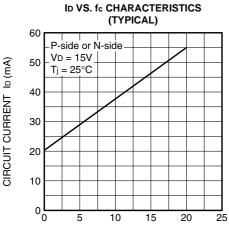


Inductive load 3 4 5 7 103

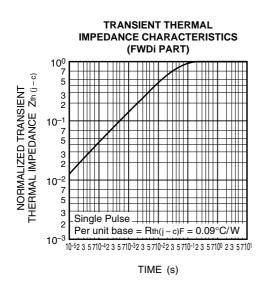
SWITCHING LOSS CHARACTERISTICS ESW(of SW(or

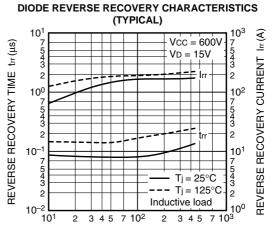
FLAT-BASE TYPE **INSULATED PACKAGE**



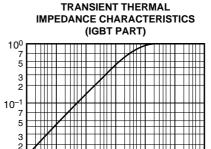


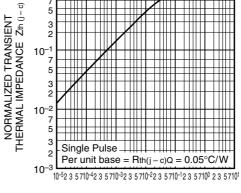
CARRIER FREQUENCY fc (kHz)





COLLECTOR RECOVERY CURRENT -Ic (A)





TIME (s)



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